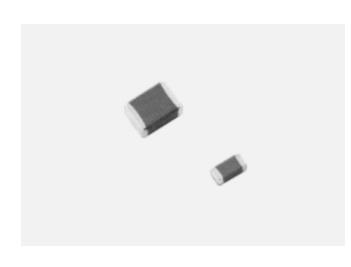
## SURFACE MOUNT MONOLITHIC CHIP CAPACITORS

250VDC TO 3.15kVDC, SL, R & B TYPES



## GHM1000/1500 Series



### **FEATURES**

- A new multi-layer structure for small, surface-mountable devices capable of operating at high-voltage.
- Sn plated external electrodes allow mounting without silver compound solder.
- The GHM1030 type and 1525/1530 types for flow and reflow soldering. All other types for reflow soldering only.

## **APPLICATIONS**

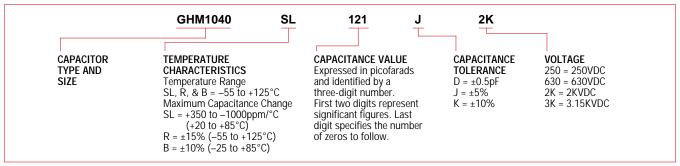
### GHM1000

- Ideal use on high-frequency pulse circuit such as snubber circuit for switching power supply, DC-DC converter, ballast (inverter fluorescent lamp). (R Characteristics)
- Ideal for use as the ballast in liquid crystal back-lighting inverters. (SL Characteristics)

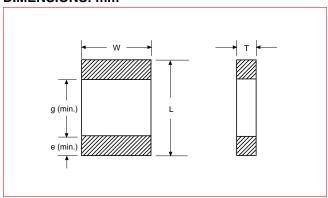
#### GHM1500

- Ideal use as hot-cold coupling for DC-DC converter.
- Ideal use on line filter and ringer detector for telephone, facsimile and modem.
- Ideal use on diode-snubber circuit for switching power supply.

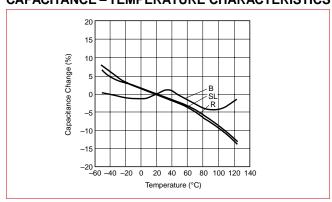
#### PART NUMBERING SYSTEM



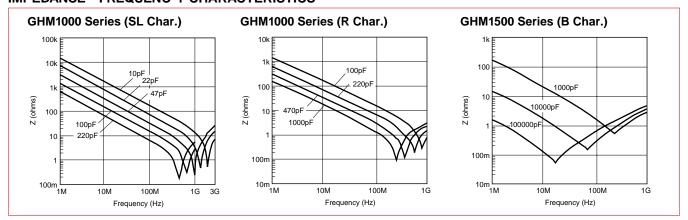
## **DIMENSIONS: mm**



### **CAPACITANCE - TEMPERATURE CHARACTERISTICS**



## **IMPEDANCE - FREQUENC Y CHARACTERISTICS**



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## SURFACE MOUNT MONOLITHIC CHIP CAPACITORS 250VDC TO 3.15kVDC, SL, R & B TYPES



## GHM1000/1500 Series

## TEMPERATURE COMPENSATING TYPE SL Characteristic (+350 to -1000ppm/°C)

Part Number	Nominal	Capacitance	DC Rated	Dimensions (mm)					Packaging Qty.
rait ivuilibei	Capacitance (pF)	Tolerance	Voltage (V)	L	W	Т	g	е	(pcs./reel)
GHM1040SL121J2K	120								
GHM1040SL151J2K	150	±5%	2k		22.02	2.0 +0 3			1000
GHM1040SL181J2K	180	±5%	∠K	4.5 ± 0.3	3.2 ± 0.3	2.U <u>-</u> 0.3			1000
GHM1040SL221J2K	220								
GHM1038SL100D3K	10	±0.5pF					2.9	0.3	
GHM1038SL120J3K	12								
GHM1038SL150J3K	15								
GHM1038SL180J3K	18								
GHM1038SL220J3K	22								
GHM1038SL270J3K	27				2.0 + 0.2	2.0 + 0.3			2000
GHM1038SL330J3K	33	±5%	3.15k		2.0 ± 0.2	2.0 ± 0.3			2000
GHM1038SL390J3K	39	±370							
GHM1038SL470J3K	47								
GHM1038SL560J3K	56								
GHM1038SL680J3K	68								
GHM1038SL820J3K	82								
GHM1040SL101J3K	100				$3.2 \pm 0.3$	2.5 +0 -0.3			500

<sup>\*1</sup>k VDC product also available. Please contact us for further details.

## HIGH DIELECTRIC CONSTANT TYPE R Characteristic (±15%)

Part Number	Nominal	Capacitance Tolerance	DC Rated Voltage (V)	Dimensions (mm)					Packaging Qty.
rait Number	Capacitance (pF)			L	W	T	g	е	(pcs./reel)
GHM1030R101K630	100	±10%	630	3.2 ± 0.2	1.6 ± 0.2	1.0 +0 -0.3	1.5	0.3	4000 3000
GHM1030R151K630	150								
GHM1030R221K630	220								
GHM1030R331K630	330								
GHM1030R471K630	470					1.25 +0 -0.3			
GHM1030R681K630	680								
GHM1030R102K630	1000								

## HIGH DIELECTRIC CONSTANT TYPE B Characteristic (±15% from -55 to +125°C; ±10% within -25 to +85°C)

Part Number	Nominal	Capacitance	DC Rated	Dimensions (mm)					Packaging Qty.
Part Number	Capacitance (pF)	Tolerance	Voltage (V)	L	W	T	g	е	(pcs./reel)
GHM1525B102K250	1000								
GHM1525B152K250	1500								
GHM1525B222K250	2200					1.0 +0			4000
GHM1525B332K250	3300			$2.0 \pm 0.2$	1.25 ± 0.2	1.0 _0.3	0.7		4000
GHM1525B472K250	4700								
GHM1525B682K250	6800								
GHM1525B103K250	10000					1.25 ± 0.2			3000
GHM1530B153K250	15000					1.0 +0			4000
GHM1530B223K250	22000		250	3.2 ± 0.2	1.6 ± 0.2				
GHM1530B333K250	33000			J.Z ± 0.Z	1.0 ± 0.2	1.25 +0 -0.3	1.5		3000
GHM1530B473K250	47000					1.6 ± 0.2	1.5		2000
GHM1535B683K250	68000			3.2 ± 0.3	2.5 ± 0.2	1.5 +0 -0.3			2000
GHM1535B104K250	100000			3.2 ± 0.3	2.3 ± 0.2	2 O ±0			1000
GHM1540B154K250	150000			4.5 ± 0.4	3.2 ± 0.3	2.0 +0 -0.3	2.5		1000
GHM1540B224K250	220000			4.5 ± 0.4	3.2 ± 0.3	2.5 +0 -0.3	2.5		500
GHM1545B334K250	330000	.100/		F 7 . O 4	F 0 . 0 4	2 O ±0	2.5	0.0	1000
GHM1545B474K250	470000	±10%		$5.7 \pm 0.4$	5.0 ± 0.4	2.0 +0 -0.3	3.5	0.3	1000
GHM1530B102K630	1000								
GHM1530B152K630	1500								
GHM1530B222K630	2200								
GHM1530B332K630	3300			$3.2 \pm 0.2$	1.6 ± 0.2	1.25 +0 -0.3			3000
GHM1530B472K630	4700						1.5		
GHM1530B682K630	6800								
GHM1530B103K630	10000								
GHM1535B153K630	15000		630	3.2 ± 0.3	2.5 ± 0.2				2000
GHM1535B223K630	22000			J.Z ± U.J	Z.J ± U.Z	1.5 +0 -0.3			2000
GHM1540B333K630	33000					1.5 _0.3			
GHM1540B473K630	47000			4.5 ± 0.4	3.2 ± 0.3		2.5		1000
GHM1540B683K630	68000			7.5 £ 0.4	J.Z ± 0.3	2.0 +0 -0.3	2.5		
GHM1540B104K630	100000					2.6 +0 -0.3			500
GHM1545B154K630	150000			E 7 . O 4	F O . O 4	2.0 +0 -0.3	2.5		1000
GHM1545B224K630	220000			5.7 ± 0.4	5.0 ± 0.4	2.7 +0 -0.3	3.5		500

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# SURFACE MOUNT MONOLITHIC CHIP CAPACITORS SPECIFICATIONS AND TEST METHODS



## GHM1000/1500 Series

			Specif	ication				
No.	It	em	Temperature Compensating Type (SL Char.)			Test N	<b>Nethod</b>	
1	Operating Temperature	e Range	–55 to +125°C			_	_	
2	Dielectric Strength		No defects or abnormalities.	No failure shall be observed when voltage in Table is applied between the terminations for 1 to 5 s, provided the charge/discharge current is less than 50mA.				
					Rated Voltage		Test Voltage	
					More than	DC1kV	120% of the rated voltage	
					630\		150% of the rated voltage	
					250\	<u> </u>	200% of the rated voltage	
3	Insulation Resistance	(I.R.)	$C \ge 0.01 \mu F$ : More than 100M $C < 0.01 \mu F$ : More than 10000	The insulation resistance shall be measured with 500 $\pm$ 50V (250 $\pm$ 50V in case of rated voltage: DC 250V) and within $60 \pm 5$ s of charging.				
4	Capacitance	9	Within the specified tolerance	).	The capacitance/0	2/D.F. shall be	e measured at 20°C at the	
5	<u> </u>		C $\geq$ 30pF: Q $\geq$ 1000 C < 30pF: Q $\geq$ 400 + 20C C: Nominal Capacitance (pF)	D.F. ≤ 0.01 (R Char.) D.F. ≤ 0.025 (B Char.)	frequency and voltage shown as follows:  Temperature Compensating Type Frequency: 1 ± 0.2MHz Voltage: 0.5 to 5V(r.m.s.)  High Dielectric Constant Type Frequency: 1 ± 0.2kHz Voltage: 1 ± 0.2V(r.m.s.)			
6	6 Capacitance Temperature Characteristics		nperature +350 to -1000ppm/°C (R Cha		Temperature Compensating Type The temperature coefficient is determined using the capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5 (+20 to +85°C) the capacitance shall be within the specified tolerance for the temperature coefficient.			
					Step		Temperature (°C)	
					1		20 ± 2	
					2	Mir	n. Operating Temp. ±3	
					3		20 ± 2	
					4	Max	x. Operating Temp. ±2	
					5	20 ± 2		
					■ High Dielectric Constant Type The range of capacitance change compared to the 20°C value within −55 to +125°C (−25 to +85°C for B Char.) shall be within the specified range.  Pretreatment Perform a heat treatment at 150 <sup>+0</sup> <sub>-10</sub> °C for 60 ± 5 min. at then let sit for 24 ± 2 h at room condition.			
7	Adhesive St of Terminat	•	No removal of the termination defects shall occur.	ns or other	shown in Fig. 1 u Then apply 10N for The soldering shat reflow method an	sing a eutecti orce in the di Il be done eit d shall be co	ting jig (glass epoxy board) ic solder. rection of the arrow. ther with an iron or using the nducted with care so that the of defects such as heat shock.  10N, 10 ± 1s Speed: 1.0mm/s Glass Epoxy Board	
0	Vibration	Canacitanas	Within the encoified telegrape		Fig. 1  Solder the capacitor to the testing jig (glass			
8	Vibration Resistance	Capacitance	Within the specified tolerance		The capacitor sha	or to the testi Il be subjected	ing jig (glass epoxy board). d to a simple harmonic motion	
	Aconstance	Q/D.F.	$C \ge 30pF$ : $Q \ge 1000$ $C < 30pF$ : $Q \ge 400 + 20C$ C: Nominal Capacitance (pF)	D.F. ≤ 0.01 (R Char.) D.F. ≤ 0.025 (B Char.)	having a total ampuniformly betweer frequency range, traversed in approfor a period of 2 h	olitude of 1.5r of the approxir from 10 to 55 oximately 1 m	mm, the frequency being varied mate limits of 10 and 55Hz. The 5Hz and return to 10Hz, shall be in. This motion shall be applied utually perpendicular directions	
						Glass Epoxy Bo	Solder Resist	

"room condition" Temperature: 15 to 35°C; Relative humidity: 45 to 75%; Atmosphere pressure: 86 to 106kPa

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# SURFACE MOUNT MONOLITHIC CHIP CAPACITORS SPECIFICATIONS AND TEST METHODS



## GHM1000/1500 Series

			Specif	ication					
No.	lt€	em	Temperature Compensating Type (SL Char.)	High Dielectric Constant Type (R or B Char.)	Test Method				
9 Deflection			100 t: 1.6	L x W (mm) a b c d 2.0 x 1.25 1.2 4.0 1.65 3.2 x 1.6 2.2 5.0 2.0 3.2 x 2.5 2.2 5.0 2.9 4.5 x 2.0 3.5 7.0 2.4 4.5 x 3.2 3.5 7.0 3.7 5.7 x 5.0 4.5 8.0 5.6	Capacitance meter	ectic solder. rection shown in Fig. either with an iron conducted with car ee of defects such a surizing d: 1.0mm/s rrize 2.	g. 3. or using the e so that the		
10	10 Solderability of Termination		75% of the terminations are t evenly and continuously.	o be soldered	Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 2 ± 0.5 s at 235 ± 5°C				
11	Resistance to Soldering	Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10%	Immersing speed: 25 ± 2.50  Preheat the capacitor at 120  Immerse the capacitor in eu	) to 150°C* for 1 m	iin. In at 260 + 5°C		
	Heat	Q/D.F.	C $\geq$ 30pF: Q $\geq$ 1000 C < 30pF: Q $\geq$ 400 + 20C C: Nominal Capacitance (pF)	D.F. ≤ 0.01 (R Char.) D.F. ≤ 0.025 (B Char.)	for 10 ± 1 s. Let sit at room condition for 24 ± 2 h, then mea Immersing speed: 25 ± 2.5mm/s  Pretreatment for high dielectric constant type Perform a heat treatment at 150 ±0.0 °C for 60 ± 5 min.				
		I.R.	$C \ge 0.01 \mu F$ : More than 100M $C < 0.01 \mu F$ : More than 10000		then let sit for 24 ± 2 h a *Preheating for more than	3.2 x 2.5mm			
		Dielectric Strength	See item 2.		1 100°C	to 120°C to 200°C	Time 1 min 1 min		
	Temperature Cycle	Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10% (R Char.) Within ±7.5% (B Char.)	Fix the capacitor to the supporting jig (glass epoxy boshown in Fig. 4 using a eutectic solder.  Perform the five cycles according to the four heat trea listed in the following table.  Let sit for 24 ± 2 h at room condition, then measure.  Step Temperature (°C) Time				
		Q/D.F.	$C \ge 30pF: Q \ge 1000$ $C < 30pF: Q \ge 400 + 20C$ C: Nominal Capacitance (pF)	D.F. ≤ 0.01 (R Char.) D.F. ≤ 0.025 (B Char.)					
		I.R.	$C \ge 0.01 \mu F$ : More than 100M $C < 0.01 \mu F$ : More than 10000		1 Min. Opera	nature ( C) ating Temp. ±3 m Temp.	Time (min) 30 ± 3 2 to 3		
		Dielectric Strength	See item 2.		3 Max. Operating Temp. ±2 30 ± 3  4 Room Temp. 2 to 3  ■ Pretreatment for high dielectric constant type Perform a heat treatment at 150 ±0 ±0 c for 60 ± 5 min. and then let sit for 24 ± 2 h at room condition.  Solder Resist Cu Fig. 4				
13	Humidity (Steady	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within ±10% (R Char.) Within ±7.5% (B Char.)	Place the capacitor at 40 $\pm$ 2°C and relative humidity 95% for 500 $^{+24}_{-0}h$ .				
	State)	Q/D.F.	$C \ge 30pF$ : $Q \ge 350$ $C < 30pF$ : $Q \ge 275 + \frac{5}{2}C$ C: Nominal Capacitance (pF)	D.F. ≤ 0.01 (R Char.) D.F. ≤ 0.05 (B Char.)	Remove and let sit for 24 ± measure.  Pretreatment for high die Perform a heat treatment	e			
		I.R.	$C \ge 0.01 \mu F$ : More than 10M ( $C < 0.01 \mu F$ : More than 1000)		then let sit for 24 $\pm$ 2 h at room condition.				
		Dielectric Strength	See item 2.				-		
14	Life	Capacitance Change	Within ±3.0% or ±0.3pF (Whichever is larger)	Within ±10% (R Char.) Within ±15% (B Char.)	Apply the voltage in following table for 1000 $^{+48}_{-0}$ h at maximum operating temperature $\pm 3^{\circ}$ C. Remove and let sit for 24 $\pm$ 2 h at room condition, th				
		Q/D.F.	$C \ge 30pF$ : $Q \ge 350$ $C < 30pF$ : $Q \ge 275 + \frac{5}{2}C$ C: Nominal Capacitance (pF)	D.F. ≤ 0.02 (R Char.) D.F. ≤ 0.05 (B Char.)	measure. The charge/discharge current is less than Pretreatment for high dielectric consta		Α.		
		I.R.	$C \ge 0.01 \mu F$ : More than 10M of $C < 0.01 \mu F$ : More than 1000N		Apply test voltage for 60 Remove and let sit for 24	$\pm$ 5 min. at test ten $\pm$ 2 h at room con	nperature. dition.		
		Dielectric Strength	See item 2.		Rated Voltage More than DC1kV	Rated voltage			